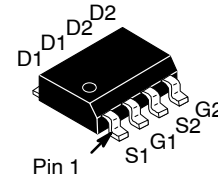


MOSFET – Dual, P-Channel, POWERTRENCH®

2.5 V Specified

FDS9933A



SOIC8
CASE 751EB

General Description

These P-Channel 2.5 V specified MOSFETs are produced using onsemi's advanced POWERTRENCH process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

Features

- -3.8 A, -20 V. $R_{DS(on)} = 0.075 \Omega, V_{GS} = -4.5 V$
 $R_{DS(on)} = 0.105 \Omega, V_{GS} = -2.5 V$
- Low Gate Charge (7 nC Typical)
- Fast Switching Speed
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- High Power and Current Handling Capability
- This Device is Pb-Free and Halide Free

Applications

- Load Switch
- DC/DC Converters
- Motor Drives

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

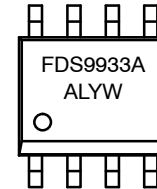
Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	-20	V
V _{GSS}	Gate-Source Voltage	±8	V
I _D	Drain Current	Continuous (Note 1a)	-3.8
		Pulsed	-20
P _D	Power Dissipation for Dual Operation		2.0
	Power Dissipation for Single Operation (Note 1a)		1.6
	(Note 1b)		1.0
	(Note 1c)		0.9
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

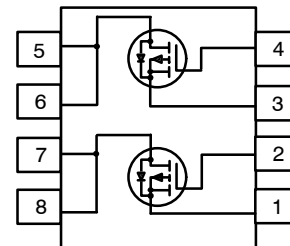
Symbol	Parameter	Value	Unit
R _{θJA}	Thermal Resistance, Junction-to-Ambient (Note 1a)	78	°C/W
R _{θJC}	Thermal Resistance, Junction-to-Case (Note 1)	40	°C/W

MARKING DIAGRAM



FDS9933A = Device Code
A = Assembly Site
L = Wafer Lot Number
YW = Assembly Start Week

PIN CONNECTIONS



ORDERING INFORMATION

Device	Package	Shipping†
FDS9933A	SOIC8	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

FDS9933A

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-20	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C	-	-16	-	$\text{mV}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}$	-	-	-1	μA
I_{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 8\text{ V}, V_{DS} = 0\text{ V}$	-	-	100	nA
I_{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -8\text{ V}, V_{DS} = 0\text{ V}$	-	-	-100	nA

ON CHARACTERISTICS (Note 2)

$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-0.4	-0.8	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C	-	2.5	-	$\text{mV}/^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -4.5\text{ V}, I_D = -3.8\text{ A}$	-	0.058	0.075	Ω
		$V_{GS} = -4.5\text{ V}, I_D = -3.8\text{ A}, T_J = 125^\circ\text{C}$	-	0.086	0.12	
		$V_{GS} = -2.5\text{ V}, I_D = -3.3\text{ A}$	-	0.084	0.105	
$I_{D(on)}$	On-State Drain Current	$V_{GS} = -4.5\text{ V}, V_{DS} = -5.0\text{ V}$	-10	-	-	A
g_{FS}	Forward Transconductance	$V_{DS} = -4.5\text{ V}, I_D = -3.8\text{ A}$	-	10	-	S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	-	600	-	pF
C_{oss}	Output Capacitance		-	175	-	pF
C_{rss}	Reverse Transfer Capacitance		-	80	-	pF

SWITCHING CHARACTERISTICS (Note 2)

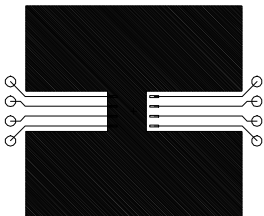
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -5\text{ V}, I_D = -0.5\text{ A}, V_{GS} = -4.5\text{ V}, R_{GS} = 6.0\ \Omega$	-	6	12	ns
t_r	Turn-On Rise Time		-	9	18	ns
$t_{d(off)}$	Turn-Off Delay Time		-	31	50	ns
t_f	Turn-Off Fall Time		-	28	42	ns
Q_g	Total Gate Charge	$V_{DS} = -10\text{ V}, I_D = -3.8\text{ A}, V_{GS} = -4.5\text{ V}$	-	7	10	nC
Q_{gs}	Gate-Source Charge		-	1.3	-	nC
Q_{gd}	Gate-Drain Charge		-	2	-	nC

DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

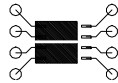
I_S	Maximum Continuous Drain-Source Diode Forward Current	-	-	-1.3	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -1.3\text{ A}$ (Note 2)	-	-0.75	-1.2	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

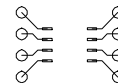
- $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



a) $78^\circ\text{C}/\text{W}$ when mounted on a 0.5 in^2 pad of 2 oz. Copper



b) $125^\circ\text{C}/\text{W}$ when mounted on a 0.02 in^2 pad of 2 oz. copper



c) $135^\circ\text{C}/\text{W}$ when mounted on a 0.003 in^2 pad of 2 oz. copper.

- Pulse Test Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2.0\%$

TYPICAL CHARACTERISTICS

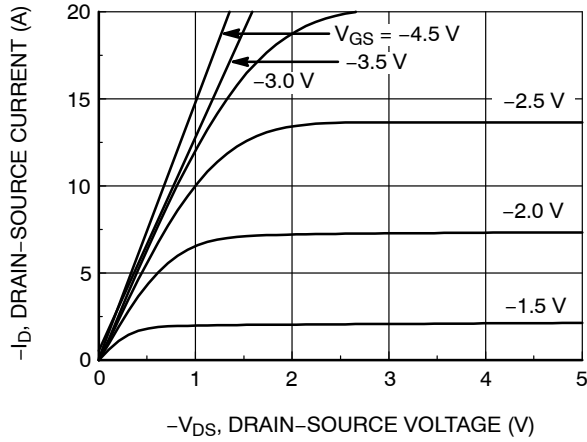


Figure 1. On-Region Characteristics

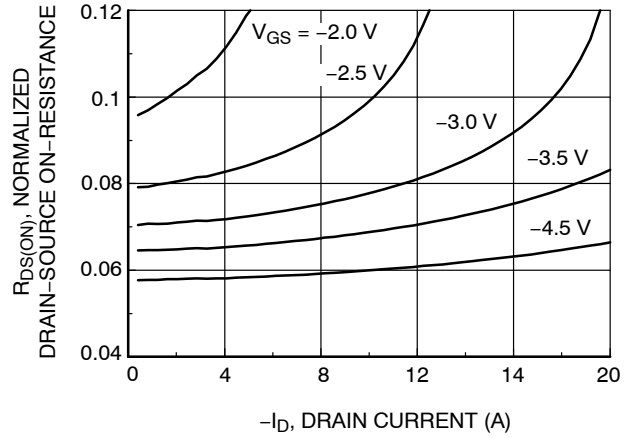


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

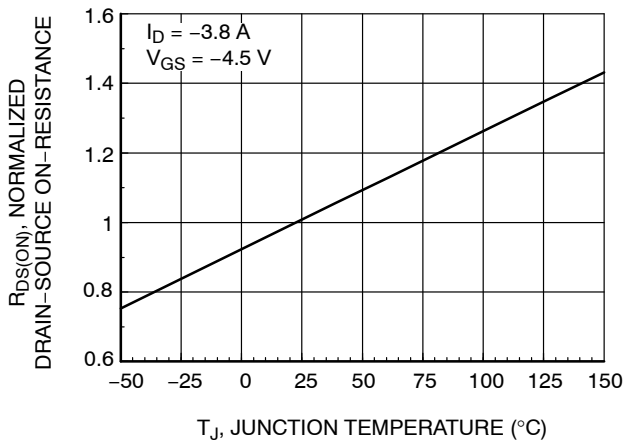


Figure 3. On-Resistance Variation with Temperature

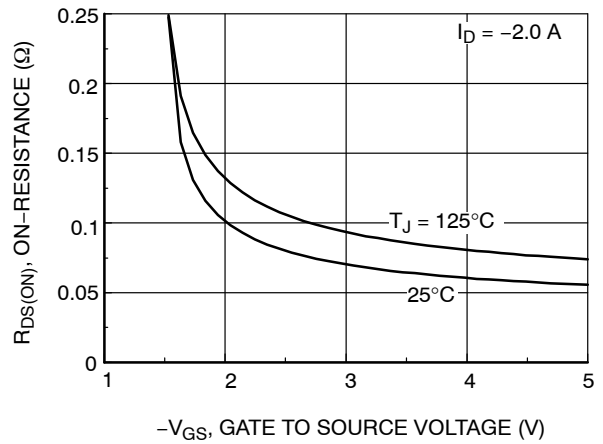


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

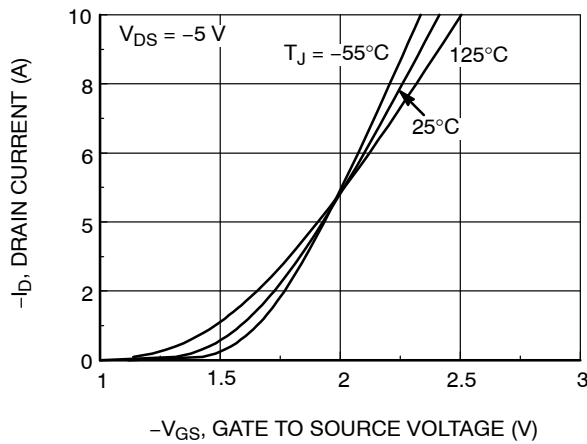


Figure 5. Transfer Characteristics

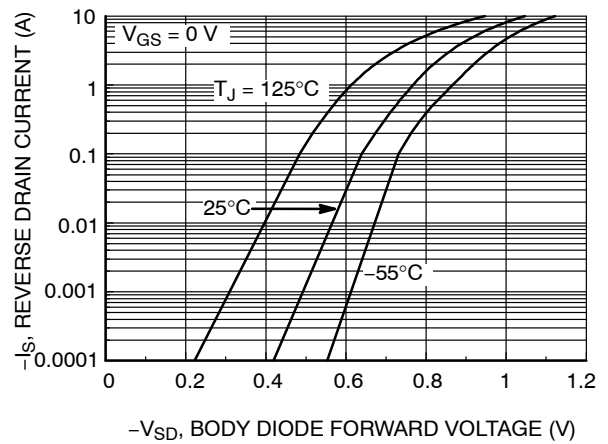


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

TYPICAL CHARACTERISTICS (continued)

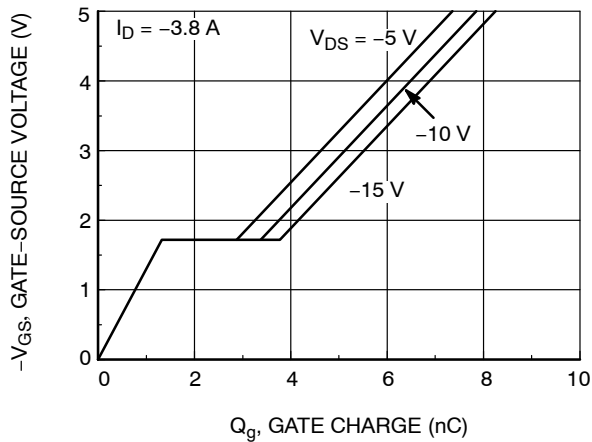


Figure 7. Gate Charge Characteristics

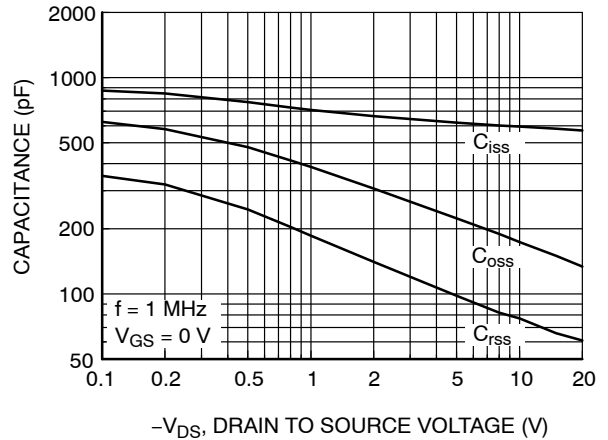


Figure 8. Capacitance Characteristics

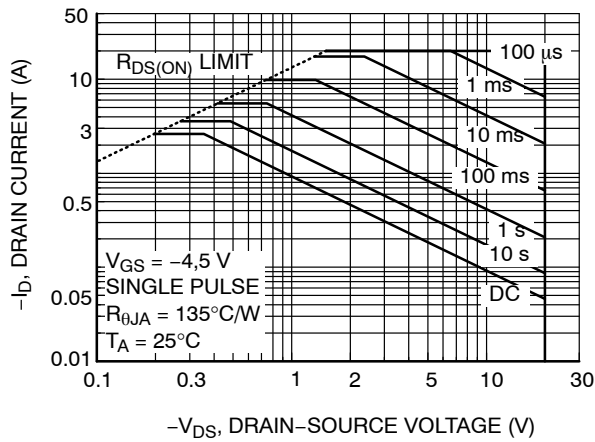


Figure 9. Maximum Safe Operating Area

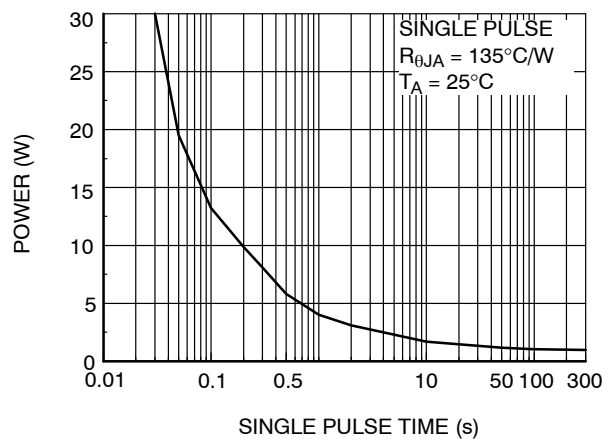


Figure 10. Single Pulse Maximum Power Dissipation

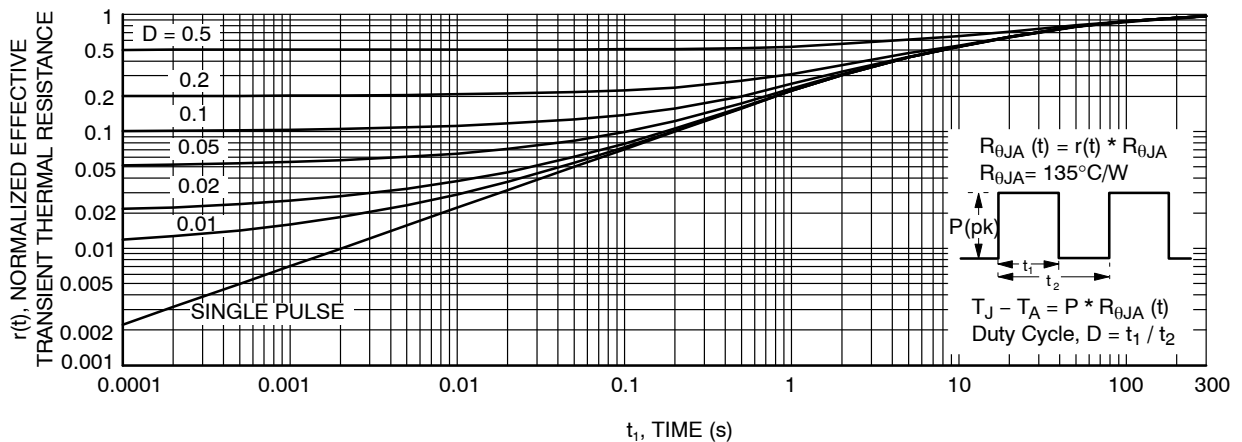


Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1c.
 Transient thermal response will change depending on the circuit board design.

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

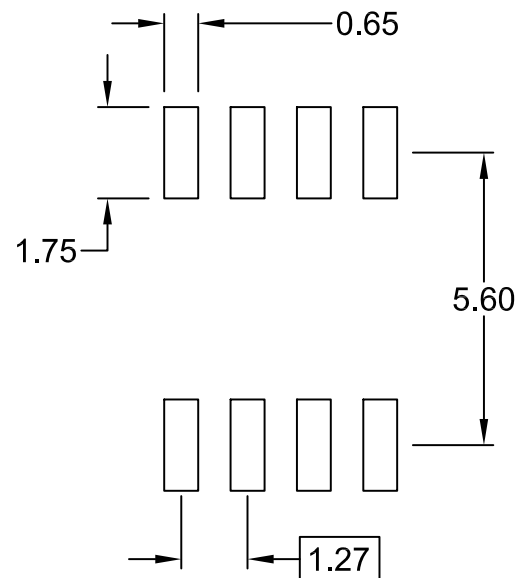


SOIC8
CASE 751EB
ISSUE A

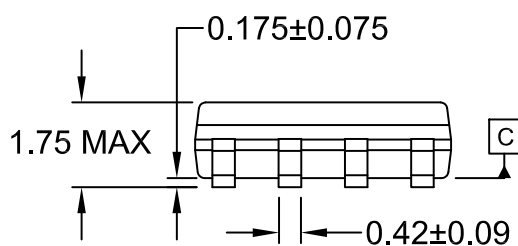
DATE 24 AUG 2017



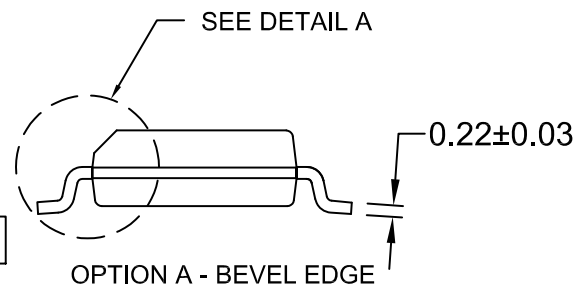
\varnothing 0.25 (M) C B A



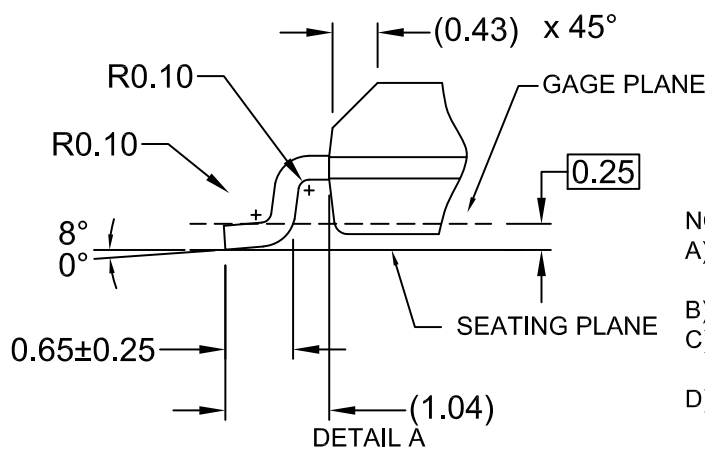
LAND PATTERN RECOMMENDATION



$\frac{1}{2}$ 0.10



OPTION B - NO BEVEL EDGE



SCALE: 2:1

NOTES:

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M

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